

MSAP

MODIFIED SEMI-ADDITIVE PROCESSING

PCB-LIKE COST AND PRODUCTIVITY FOR SUBSTRATE-LIKE THIN, FINE-PITCH DESIGNS

MacDermid Enthone Electronics Solutions offers the industry's most complete high performance portfolio of products which encompasses every process step.

Copper Reduction

CircuEtch 100

Dry Film Adhesion

MultiPrep 200

Differential Etch

CircuEtch 200

LDD Pretreatment

MultiBond 500

Dry Film Developer

Developer 45 Plus

Innerlayer Adhesion

MultiBond 500

Post LDD Conversion

CoreClean

Pattern Plate Via Fill

MacuSpec AVF

MacuSpec VF-TH

Solder Mask Adhesion

MultiPrep 200

Primary Metallization

System Desmear

Shadow LE, Eclipse LE

M-Copper Series

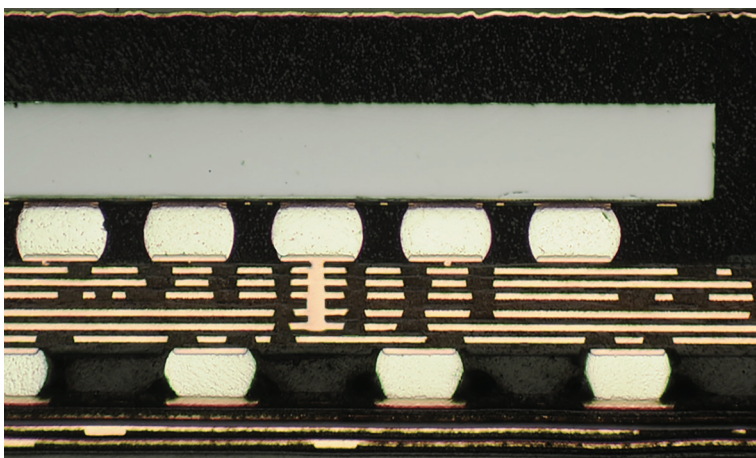
Dry Film Stripper

UltraStrip LDI

Final Finish

ENTEK PLUS HT

Affinity ENIG/ENEPIG



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